## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

| | | |
|---|---|---|
| **1.1 Company** |  | **STMicroelectronics International N.V** |
| **1.2 PCN No.** | | MDG/22/13482 |
| **1.3 Title of PCN** | | STM32G0B0x, STM32G0B1x and STM32G0C1x 512K - product enhancement |
| **1.4 Product Category** | | STM32G0B0x,<br>STM32G0B1x,<br>STM32G0C1x |
| **1.5 Issue date** | | 2022-06-28 |

### 2. PCN Team

| | |
|---|---|
| **2.1 Contact supplier** | |
| **2.1.1 Name** | ROBERTSON HEATHER |
| **2.1.2 Phone** | +1 8475853058 |
| **2.1.3 Email** | heather.robertson@st.com |
| **2.2 Change responsibility** | |
| **2.2.1 Product Manager** | Ricardo Antonio DE SA EARP |
| **2.1.2 Marketing Manager** | Veronique BARLATIER |
| **2.1.3 Quality Manager** | Pascal NARCHE |

### 3. Change

| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
|---|---|---|
| General Product & Design | Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix | TSMC FAB14 (Taiwan) |

### 4. Description of change

| | Old | New |
|---|---|---|
| **4.1 Description** | STM32G0B0x, STM32G0B1x and STM32G0C1x - (Die467– cut1.0 revision A) product has limitation as described in Errata Sheets.<br>- ES0547 (Rev 1 - January 12 2021) for STM32G0B0CE/KE/RE/VE device<br>- ES0548 (Rev 1 - January 12 2021) for STM32G0B1xB/xC/xE device<br>- ES0549 (Rev 1 - January 12 2021) for STM32G0C1xC/xE device<br><br>Limitations:<br>- Device lock in case of OPT bytes mismatch<br>- Flash memory PCROP area weakness<br>- SRAM contents corrupted upon entry in Standby<br>- ADC Offset calibration improvements<br>- Wakeup capability GPIO's not configurable after wakeup | STM32G0B0x, STM32G0B1x and STM32G0C1x 512K (Die467– cut1.1 revision Z)  product enhancement fixes those limitations as described in Errata Sheet.<br>- ES0547 (Rev 2 - April 11 2022) for STM32G0B0CE/KE/RE/VE device<br>- ES0548 (Rev 2 - April 11 2022) for STM32G0B1xB/xC/xE device<br>- ES0549 (Rev 2 - April 11 2022) for STM32G0C1xC/xE device<br><br>Enhancements:<br>- Device lock in case of OPT bytes mismatch  - fixed<br>- Flash memory PCROP area weakness – fixed<br>- TIM16 and TIM17 are unduly clocked by SYSCLK – fixed<br>- ADC Offset calibration improved<br>- Wakeup capability GPIO's not configurable after wakeup - fixed<br>- Device IDCODE updated |
| **4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?** | Functionality enhancement as indicated in Errata Sheets: ES0547, ES0548 & ES0549 | |

### 5. Reason / motivation for change

| | |
|---|---|
| **5.1 Motivation** | The strategy of ST GPM Division is to increase the robustness and improve performances, quality and functionality of our products. This is achieved by introducing new die revision for STM32G0B0x , STM32G0B1x and STM32G0Cx products. |
| **5.2 Customer Benefit** | SERVICE IMPROVEMENT |

### 6. Marking of parts / traceability of change

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|---|---|
| **6.1 Description** | Traceability ensured by ST internal tools.<br>Die revision changes from "A" to "Z" on Package Marking |

| 7. Timing / schedule | |
|---|---|
| **7.1 Date of qualification results** | 2022-06-30 |
| **7.2 Intended start of delivery** | 2022-08-15 |
| **7.3 Qualification sample available?** | Upon Request |

| 8. Qualification / Validation | | | |
|---|---|---|---|
| **8.1 Description** | 13482 MDG-MCD-RER1918_STM32G0Bx_Die 467_Reliability Evaluation Report_rev1.4.pdf | | |
| **8.2 Qualification report and qualification results** | Available (see attachment) | **Issue Date** | 2022-06-28 |

| 9. Attachments (additional documentations) |
|---|
| 13482 Public product.pdf<br>13482 MDG-MCD-RER1918_STM32G0Bx_Die 467_Reliability Evaluation Report_rev1.4.pdf<br>13482 PCN13482_Additional information.pdf |

| 10. Affected parts | | |
|---|---|---|
| **10. 1 Current** | | **10.2 New (if applicable)** |
| **10.1.1 Customer Part No** | **10.1.2 Supplier Part No** | **10.1.2 Supplier Part No** |
| | STM32G0B0RET6 | |
| | STM32G0B1CCU6 | |
| | STM32G0B1CET6N | |
| | STM32G0B1CEU6 | |
| | STM32G0B1KCT6 | |
| | STM32G0B1KET6 | |
| | STM32G0B1KET6N | |
| | STM32G0B1KEU6 | |
| | STM32G0B1RET6 | |
| | STM32G0B1VET6 | |
| | STM32G0C1RET6 | |

# Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

*PCN  Title :* STM32G0B0x, STM32G0B1x and STM32G0C1x 512K - product enhancement

*PCN  Reference :* MDG/22/13482

*Subject :* Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| | | |
|---|---|---|
| STM32G0B0RET6 | STM32G0C1KCU6 | STM32G0B1RCT7 |
| STM32G0B1KCT6N | STM32G0B1CET6 | STM32G0C1MCT6 |
| STM32G0C1CET6 | STM32G0B1KET6N | STM32G0B1VEI6 |
| STM32G0C1CEU6TR | STM32G0B1KCU7TR | STM32G0C1RCT3 |
| STM32G0B0CET6TR | STM32G0B1KET6 | STM32G0C1MET6 |
| STM32G0C1KCU6N | STM32G0B1VBT6 | STM32G0B1RCI6N |
| STM32G0B1KCT6 | STM32G0B1CBU6TR | STM32G0C1KET6N |
| STM32G0B1VCT6 | STM32G0B1KBT6 | STM32G0C1VET6 |
| STM32G0B1CET6TR | STM32G0B1RET6 | STM32G0B1RBI6N |
| STM32G0B1MBT6 | STM32G0B1VET6 | STM32G0B1KCU6 |
| STM32G0B1RBT6 | STM32G0C1KEU6N | STM32G0B1KBU6 |
| STM32G0B1CCU6TR | STM32G0B1KEU7TR | STM32G0B1CCU6N |
| STM32G0B1CCT6TR | STM32G0B1REI6N | STM32G0C1KCT6N |
| STM32G0B1CCU6NTR | STM32G0B0VET6 | STM32G0B1RBT6N |
| STM32G0B1KEU6 | STM32G0B1CBU6 | STM32G0C1KEU6 |
| STM32G0B1KBU3N | STM32G0B1CBT6 | STM32G0B1CBU3 |
| STM32G0B1CEU6N | STM32G0B1KEU6N | STM32G0B1VBI6 |
| STM32G0B1KCU7 | STM32G0B1RCT6TR | STM32G0B1RET6N |
| STM32G0B1CCU6 | STM32G0B1MET6 | STM32G0B1CBU6N |
| STM32G0B0CET6 | STM32G0C1CCU6 | STM32G0B1CET6N |
| STM32G0B1CEU6 | STM32G0C1CEU6 | STM32G0B1KEU7 |
| STM32G0C1RCT6 | STM32G0B1KBU6N | STM32G0C1VCT6 |
| STM32G0C1RET6 | STM32G0B1KCU6N | STM32G0B1CBT6N |
| STM32G0B1MCT6 | STM32G0B1RCT6 | STM32G0B1KBU3NTR |
| STM32G0C1KET6 | STM32G0B1RCI6NTR | STM32G0B0RET6TR |
| STM32G0B1KBT6N | STM32G0B1NEY6TR | STM32G0B1CCT6 |
| STM32G0B0KET6 | | |

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